



DESCRIPTION

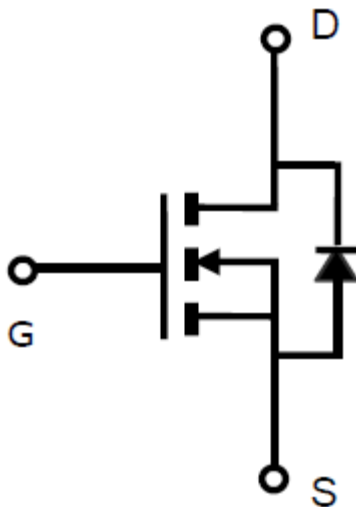
The AM3414 is the N-Channel logic enhancement mode power field effect transistor is produced using high cell density.

Advanced trench technology to provide excellent $R_{DS(ON)}$ low gate charge and operation with gate as 1.8V.

This device is suitable for use as a load switch or other general applications.

The AM3414 is available in SOT-23 Package

P-CHANNEL MOSFET



FEATURES

- 20V/5.0A, $R_{DS(ON)} = 30m\Omega$ (typ.)@ $V_{GS} = 4.5V$
- 30V/4.5A, $R_{DS(ON)} = 42m\Omega$ (typ.)@ $V_{GS} = 2.5V$
- 30V/3.8A, $R_{DS(ON)} = 50m\Omega$ (typ.)@ $V_{GS} = 1.8V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and Maximum DC current capability
- RoHs Compliant
- Available in SOT-23 package

APPLICATIONS

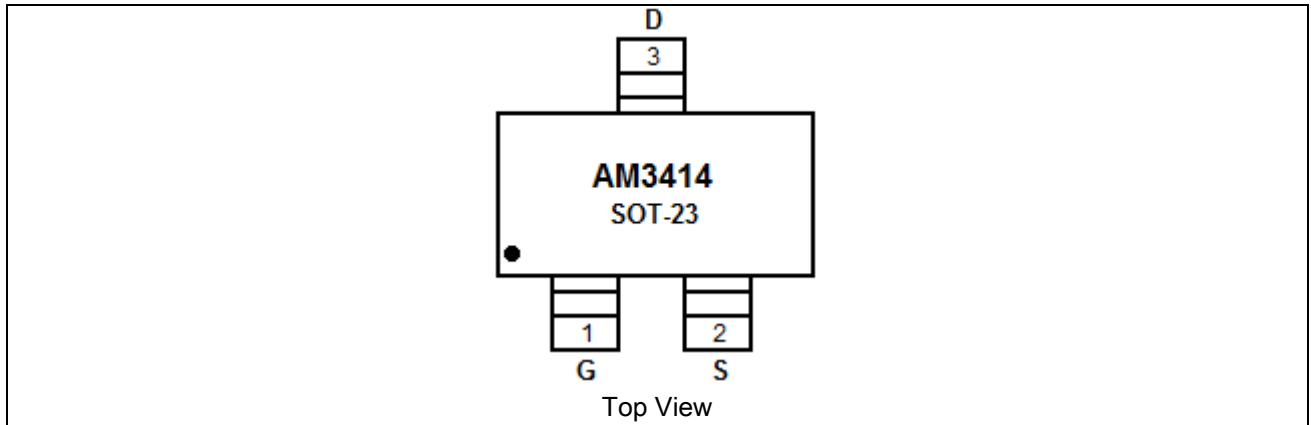
- Power Management in Note book
- Portable Equipment
- DSC
- LCD Display inverter
- Battery Powered System

ORDERING INFORMATION

| Package Type | Part Number | |
|---|-------------------------------------|------------|
| SOT-23 | E3 | AM3414E3R |
| | | AM3414E3VR |
| Note | V: Green Package R : Tape & Reel | |
| AiT provides all Pb free products Suffix " V " means Green Package | | |



PIN DESCRIPTION



| Pin # | Symbol | Function |
|-------|--------|----------|
| 1 | G | Gate |
| 2 | S | Source |
| 3 | D | Drain |



ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ Unless otherwise noted

| | | | | |
|---|--------------------------|---|-----------------------|--|
| V_{DSS} , Drain-Source Voltage | | | | 20 V |
| V_{GSS} , Gate-Source Voltage | | | | ± 12 V |
| I_D | Continuous Drain Current | $T_C = 25^\circ\text{C}^{\text{Note1}}$ | $V_{GS} = 10\text{V}$ | 5.0 A |
| | Continuous Drain Current | $T_C = 70^\circ\text{C}^{\text{Note1}}$ | | 4.0 A |
| I_{DM} , Pulsed Drain Current ^{†Note2} | | | | 20 A |
| P_D , Power Dissipation | | $T_A = 25^\circ\text{C}$ | | 1.4 W |
| | | $T_A = 70^\circ\text{C}$ | | 0.9 W |
| T_J , Operation Junction Temperature | | | | -55°C to 150°C |
| T_{STG} , Storage Temperature Range | | | | -55°C to 150°C |

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

NOTE1: The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

NOTE2: The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

THERMAL INFORMATION

| Symbol | Parameter | Typ. | Max | Unit |
|-----------------|--|------|-----|---------------------------|
| $R_{\theta JA}$ | Thermal Resistance-Junction to Ambient ^{Note1} Steady-State | - | 120 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JL}$ | Thermal Resistance Junction to Lead ^{Note1} Steady-State | - | 80 | $^\circ\text{C}/\text{W}$ |

NOTE1: The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.



ELECTRICAL CHARACTERISTICS

T_J = 25°C Unless otherwise specified

| Parameter | Symbol | Conditions | Min | Type | Max | Units |
|--|-----------------------|--|-----|------|------|-------|
| Static Parameters | | | | | | |
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} =0V, I _D =-250μA | 20 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =-250μA | 0.5 | | 1.0 | V |
| Gate Leakage Current | I _{GSS} | V _{DS} =0V, V _{GS} =±12V | | | ±100 | nA |
| Zero Gate Voltage, Drain-Source Leakage Current | I _{DSS} | V _{DS} =20V, V _{GS} =0V T _J =25°C | | | 1 | μA |
| | | V _{DS} =-20V, V _{GS} =0V T _J =55°C | | | 5 | |
| Drain-source On-Resistance ^{Note2} | R _{DS(ON)} | V _{GS} =4.5V, I _D = 5.0A | | 30 | 38 | mΩ |
| | | V _{GS} =2.5V, I _D = 4.5A | | 42 | 48 | |
| | | V _{GS} =1.8V, I _D = 3.8A | | 50 | 65 | |
| Forward Transconductance | G _{fs} | V _{DS} = 15V, I _D = 5.0A | | 30 | | S |
| Source-Drain Diode | | | | | | |
| Diode Forward Voltage | V _{SD} | I _S =1.7A, V _{GS} =0V | | 0.9 | 1.2 | V |
| Continuous Source Current ^{Note1 Note3} | I _S | | | | 6 | A |
| Dynamic Parameters | | | | | | |
| Total Gate Charge | Q _g (4.5V) | V _{DS} = 10V | | 11 | 13 | nC |
| Gate-Source Charge | Q _{gs} | V _{GS} = 4.5V | | 1.45 | | |
| Gate-Drain Charge | Q _{gd} | I _D ≅ 5.0A | | 2.3 | | |
| Input Capacitance | C _{iss} | V _{DS} = 10V | | 578 | | pF |
| Output Capacitance | C _{oss} | V _{GS} =0V | | 116 | | |
| Reverse Transfer Capacitance | C _{rss} | f=1MHz | | 96 | | |
| Turn-On Time | t _{d(on)} | V _{DD} = 10V | | 14.5 | 25 | nS |
| | t _r | I _D = 1.0A | | 42 | 62 | |
| Turn-Off Time | t _{d(off)} | V _{GEN} = 4.5V | | 46 | 67 | |
| | t _f | R _G =6Ω | | 34 | 43 | |

NOTE1: The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.

NOTE2: The data tested by pulsed , pulse width ≤ 300uS , duty cycle ≤ 2%

NOTE3: The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.



TYPICAL PERFORMANCE CHARACTERISTICS

$T_A=25^\circ\text{C}$ Unless Specified

Figure 1. Output Characteristics

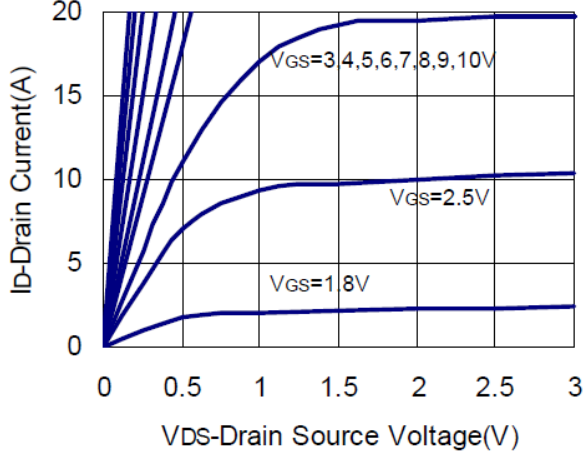


Figure 2. Drain-Source On Resistance

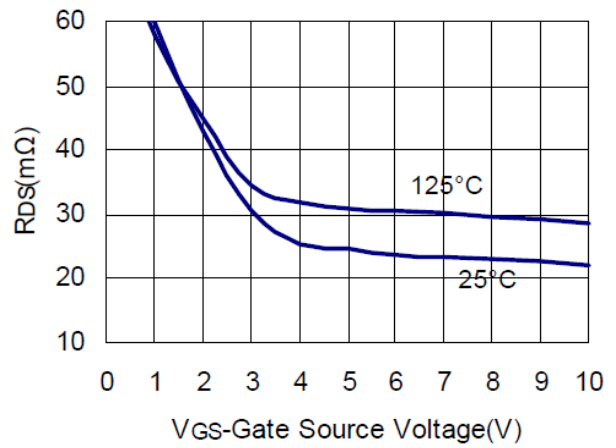


Figure 3. Drain Source On Resistance

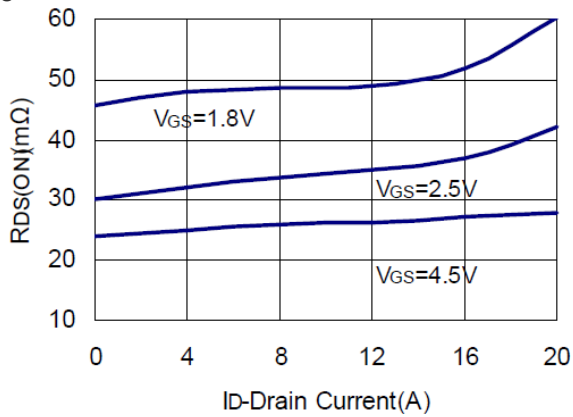


Figure 4. Gate Threshold Voltage

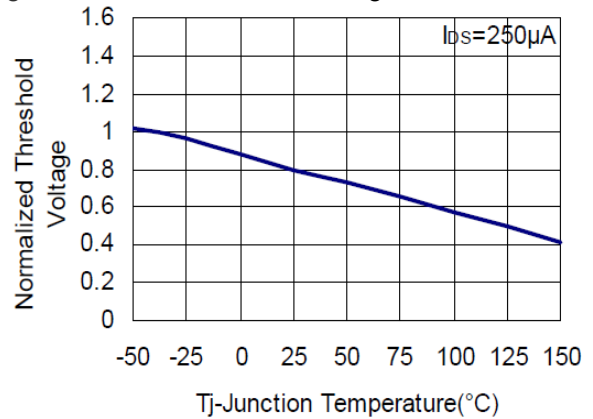


Figure 5. Gate Charge

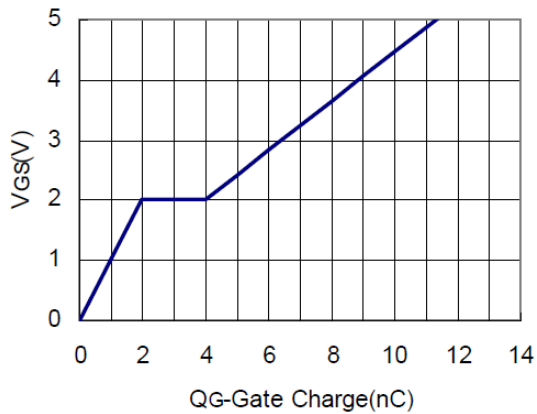


Figure 6. Drain Source Resistance

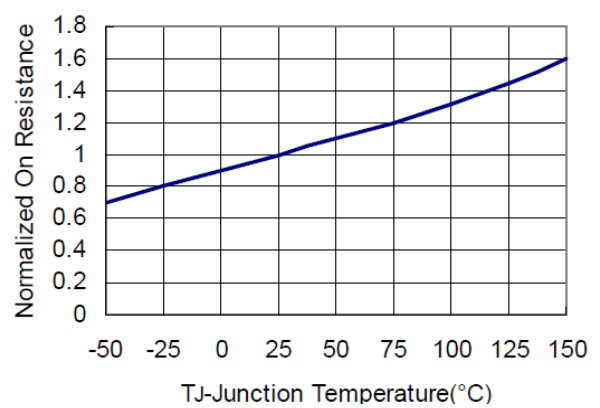




Figure7. Capacitance

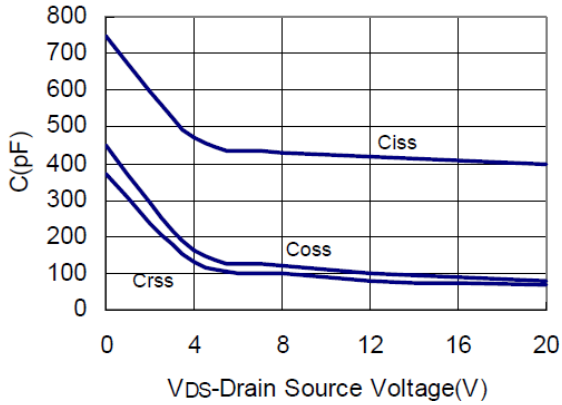


Figure 8. Source Drain Diode Forward

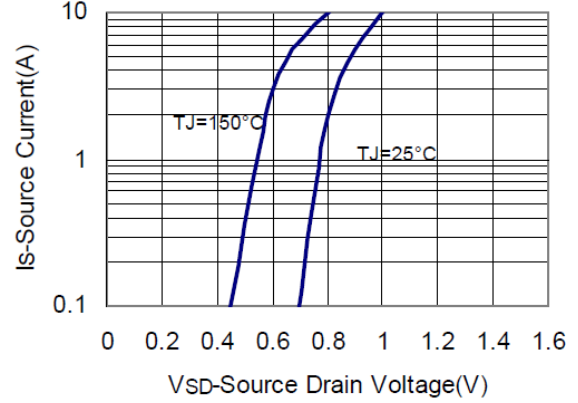


Figure9. Power Dissipation

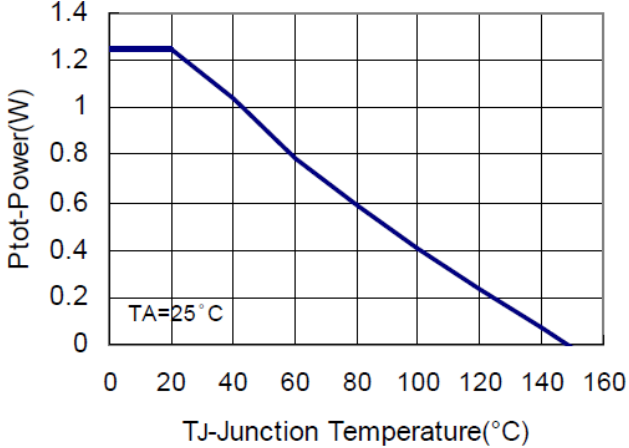


Figure10. Drain Current

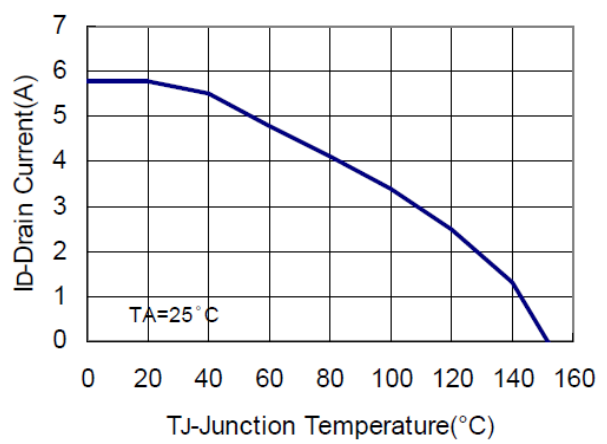
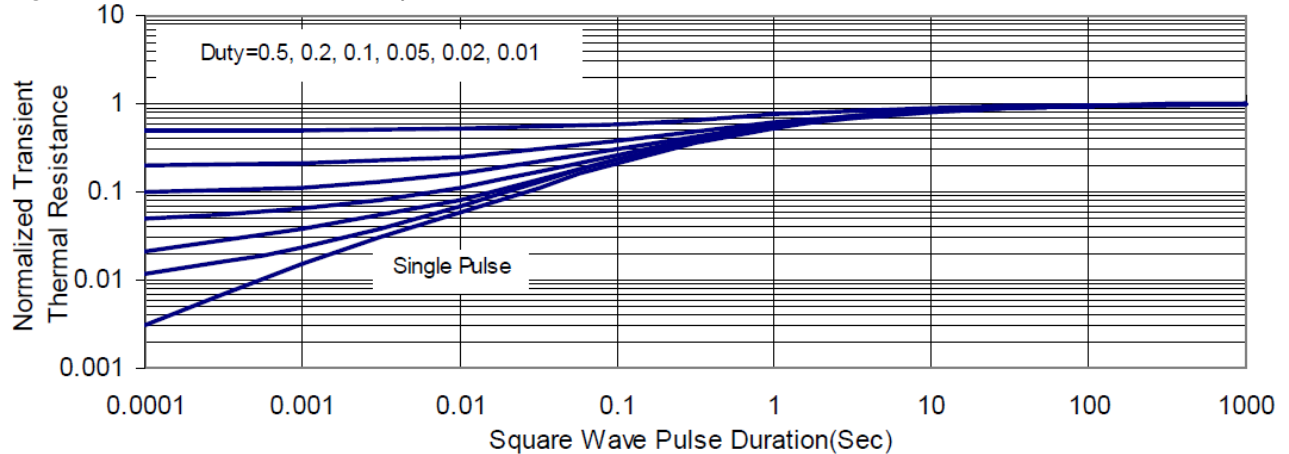


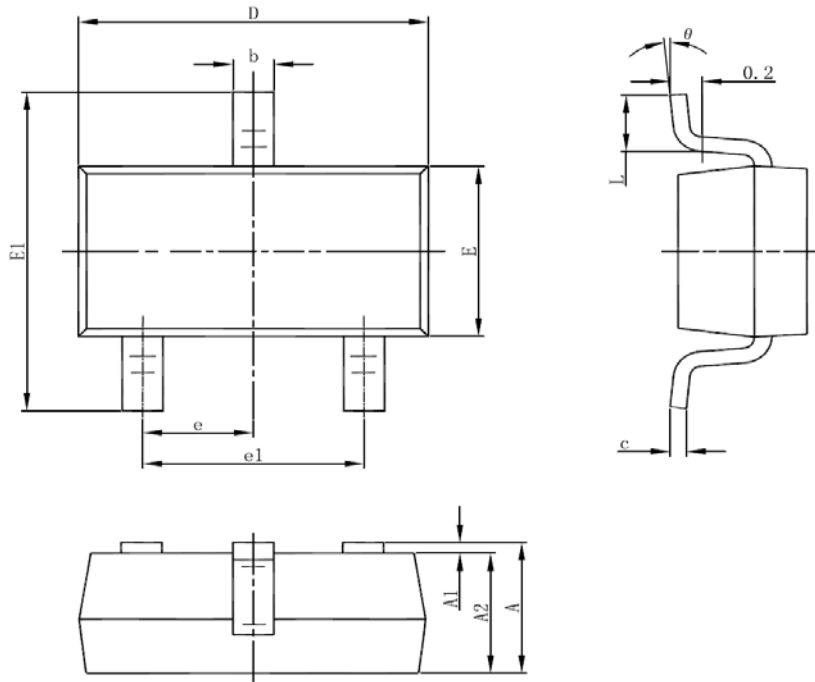
Figure11. Thermal Transient Impedance





PACKAGE INFORMATION

Dimension in SOT-23 Package (Unit: mm)



| SYMBOL | MIN | MAX |
|--------|------------|-------|
| A | 1.050 | 1.250 |
| A1 | 0.000 | 0.100 |
| A2 | 1.050 | 1.150 |
| b | 0.300 | 0.500 |
| c | 0.100 | 0.200 |
| D | 2.820 | 3.020 |
| E | 1.500 | 1.700 |
| E1 | 2.650 | 2.950 |
| e | 0.950(BSC) | |
| e1 | 1.800 | 2.000 |
| L | 0.300 | 0.600 |
| θ | 0° | 8° |



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